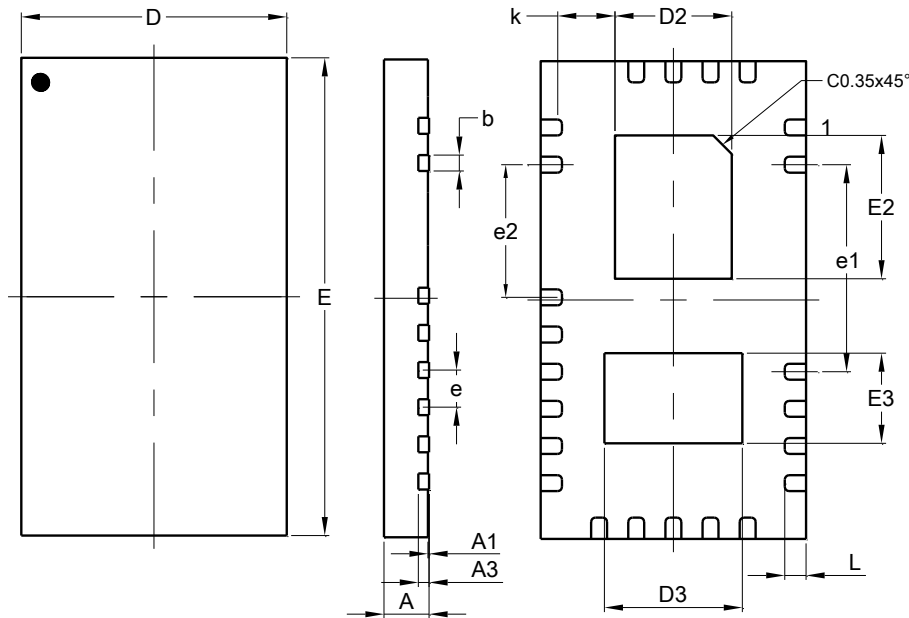


**Package Outline Dimensions**

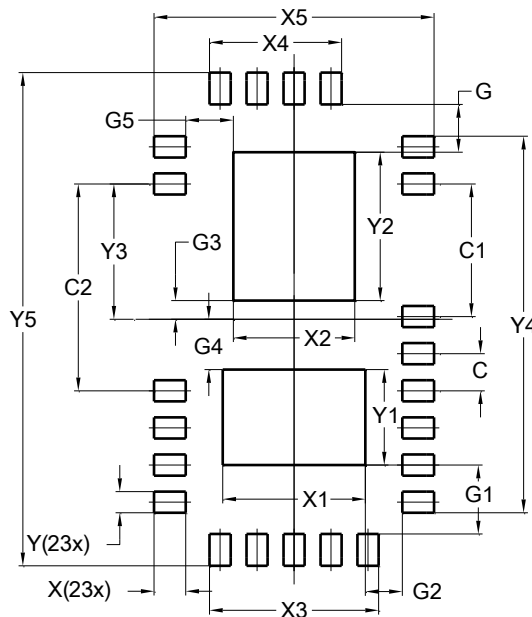
V-QFN5090-23 (Type A1)



V-QFN5090-23 (Type A1)			
Dim	Min	Max	Typ
A	0.80	0.90	0.85
A1	0.00	0.05	0.02
A3	0.203 REF		
b	0.25	0.35	0.30
D	4.90	5.10	5.00
D2	2.15	2.25	2.20
D3	2.55	2.65	2.60
E	8.90	9.10	9.00
E2	2.65	2.75	2.70
E3	1.65	1.75	1.70
e	0.70 BSC		
e1	3.90 BSC		
e2	2.50 BSC		
k	0.20	--	--
L	0.35	0.45	0.40
All Dimensions in mm			

**Suggested Pad Layout**

V-QFN5090-23 (Type A1)



Dimensions	Value (in mm)
C	0.700
C1	2.500
C2	3.900
G	0.900
G1	1.300
G2	0.700
G3	0.350
G4	0.950
G5	0.900
X	0.600
X1	2.700
X2	2.300
X3	3.200
X4	2.500
X5	5.300
Y	0.400
Y1	1.800
Y2	2.800
Y3	2.500
Y4	7.100
Y5	9.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.